XILINX®

PK421 (v1.0) September 27, 2010

100% Material Declaration Data Sheet FG676 Package for Spartan-6 FPGAs

Average Weight: 3.0820g

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
Silicon Die					**0.074896**	**2.430**
	Silicon	7440-21-3	100.00		0.074896	
Die Attach Material					**0.013303**	**0.432**
	Silver	7440-22-4	77.50		0.010310	
	Bismaleimide Monomer	Trade Secret	15.00		0.001995	
	Acrylate Monomer	Trade Secret	7.50		0.000998	
Mold Compound					**1.387604**	**45.023**
	Solid Epoxy Resin	Trade Secret	5.00		0.069380	
	Phenol Resin	Trade Secret	5.00		0.069380	
	Fused Silica	60676-86-0	87.45		1.213460	
	Metal Hydroxide	Trade Secret	2.00		0.027752	
	Carbon Black	1333-86-4	0.55		0.007632	
Gold Wire					**0.018243**	**0.592**
	Gold	7440-57-5	99.05		0.018069	
	Palladium	7440-05-3	0.95		0.000173	
	Calcium	7440-70-2	0.00		0.000000	
Solder Balls					**0.665707**	**21.600**
	Tin	7440-31-5	63.00		0.419395	
	Lead	7439-92-1	37.00		0.246312	

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Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
Substrate					**0.922260**	**29.924**
	Copper	7440-50-8	20.90		0.192724	
	Nickel	7440-02-0	2.11		0.019454	
	Gold	7440-57-5	0.37		0.003423	
Core	Epoxy Resin	Trade Secret	20.31		0.187317	
	Inorganic Filler	21645-51-2	9.12		0.084078	
	Fiberglass	65997-17-3	20.31		0.187317	
	Copper	7440-50-8	3.04		0.028026	
Solder Mask	Talc	14807-96-6	1.02		0.009407	
	Morpholine Derivative	Trade Secret	1.05		0.009684	
	Barium Sulfate	7727-43-7	12.12		0.111759	
	Silica	7631-86-9	0.27		0.002484	
	Dipropylene Glycol Monomethyl Ether	34590-94-8	5.46		0.050382	
	Epoxy Resin	85954-11-6	3.92		0.036193	

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
09/27/10	1.0	Initial Xilinx release.

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